

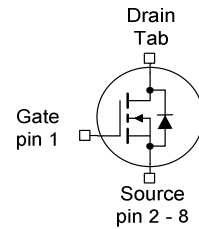
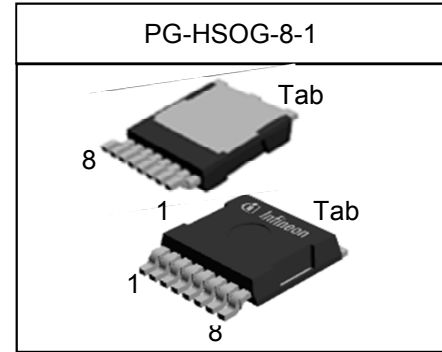
OptiMOS™-T2 Power-Transistor

Features

- N-channel - Enhancement mode
- AEC qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green product (RoHS compliant)
- Ultra low Rds(on)
- 100% Avalanche tested

Product Summary

V_{DS}	40	V
$R_{DS(on)}$	1.5	mΩ
I_D	180	A



Type	Package	Marking
IAUS180N04S4N015	PG-HSOG-8-1	A04S4N15

Maximum ratings, at $T_j=25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$T_C=25\text{ °C}, V_{GS}=10\text{V}^{(1)}$	180	A
		$T_C=100\text{ °C}, V_{GS}=10\text{V}^{(2)}$	169	
Pulsed drain current ²⁾	$I_{D,pulse}$	$T_C=25\text{ °C}$	720	
Avalanche energy, single pulse ²⁾	E_{AS}	$I_D=90\text{ A}$	320	mJ
Avalanche current, single pulse	I_{AS}	-	180	A
Gate source voltage	V_{GS}	-	±20	V
Power dissipation	P_{tot}	$T_C=25\text{ °C}$	166	W
Operating and storage temperature	T_j, T_{stg}	-	-55 ... +175	°C

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Thermal characteristics²⁾

Thermal resistance, junction - case	R_{thJC}	-	-	-	0.9	K/W
SMD version, device on PCB	R_{thJA}	minimal footprint	-	-	62	
		6 cm ² cooling area ³⁾	-	-	40	

• Green product (RoHS compliant)

Electrical characteristics, at $T_j=25\text{ °C}$, unless otherwise specified

Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}$, $I_D=1\text{ mA}$	40	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_D=110\text{ }\mu\text{A}$	2.0	3.0	4.0	
Zero gate voltage drain current	I_{DSS}	$V_{DS}=40\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=25\text{ °C}$	-	0.1	10	μA
		$V_{DS}=18\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=85\text{ °C}^{2)}$	-	1	20	
Gate-source leakage current	I_{GSS}	$V_{GS}=20\text{ V}$, $V_{DS}=0\text{ V}$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{ V}$, $I_D=100\text{ A}$	-	1.2	1.5	m Ω

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic characteristics²⁾

Input capacitance	C_{iss}	$V_{GS}=0\text{ V}, V_{DS}=25\text{ V},$ $f=1\text{ MHz}$	-	8218	10683	pF
Output capacitance	C_{oss}		-	1840	2392	
Reverse transfer capacitance	C_{rss}		-	63	145	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=20\text{ V}, V_{GS}=10\text{ V},$ $I_D=180\text{ A}, R_G=3.5\ \Omega$	-	25	-	ns
Rise time	t_r		-	10	-	
Turn-off delay time	$t_{d(off)}$		-	32	-	
Fall time	t_f		-	25	-	

Gate Charge Characteristics²⁾

Gate to source charge	Q_{gs}	$V_{DD}=32\text{ V}, I_D=180\text{ A},$ $V_{GS}=0\text{ to }10\text{ V}$	-	47	61	nC
Gate to drain charge	Q_{gd}		-	15	38	
Gate charge total	Q_g		-	103	134	
Gate plateau voltage	$V_{plateau}$		-	5.6	-	V

Reverse Diode

Diode continuous forward current ²⁾	I_S	$T_C=25\text{ }^\circ\text{C}$	-	-	180	A
Diode pulse current ²⁾	$I_{S,pulse}$		-	-	720	
Diode forward voltage	V_{SD}	$V_{GS}=0\text{ V}, I_F=100\text{ A},$ $T_J=25\text{ }^\circ\text{C}$	-	0.9	1.3	V
Reverse recovery time ²⁾	t_{rr}	$V_R=20\text{ V}, I_F=50\text{ A},$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	58	-	ns
Reverse recovery charge ²⁾	Q_{rr}		-	64	-	nC

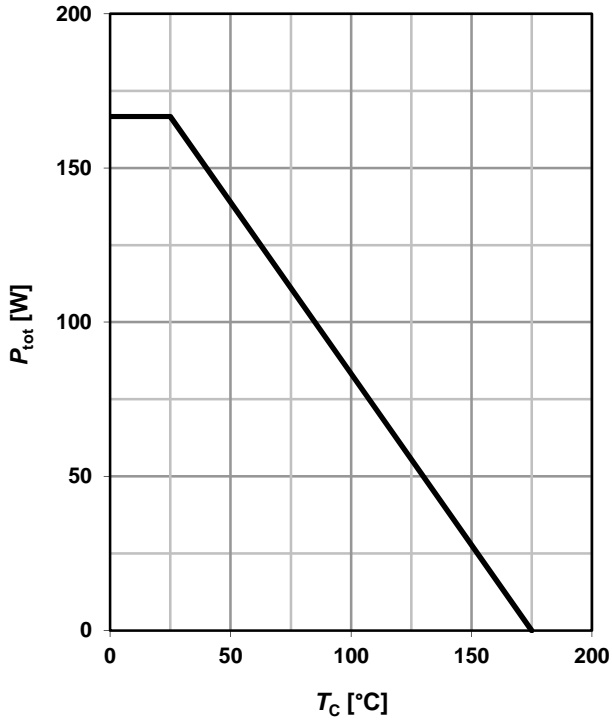
¹⁾ Current is limited by bondwire; with an $R_{thJC} = 0.9\text{ K/W}$ the chip is able to carry 255A at 25°C.

²⁾ Defined by design. Not subject to production test.

³⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

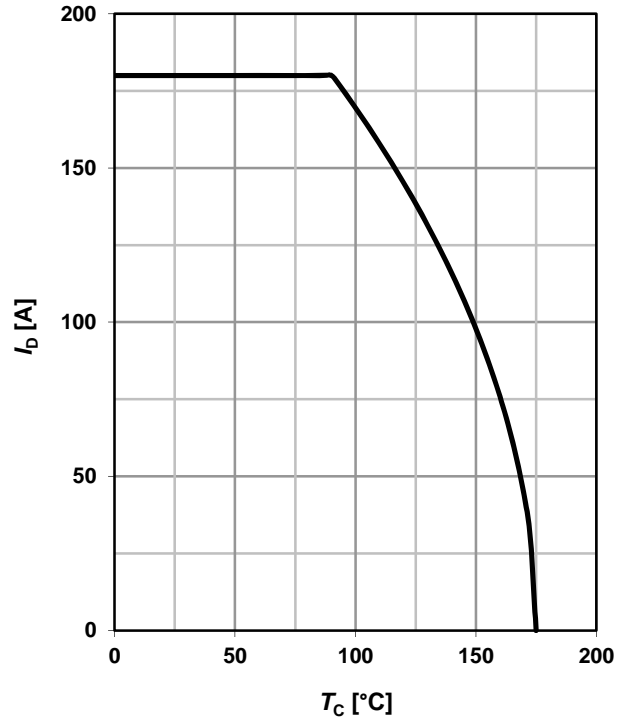
1 Power dissipation

$P_{tot} = f(T_C); V_{GS} \geq 6 V$



2 Drain current

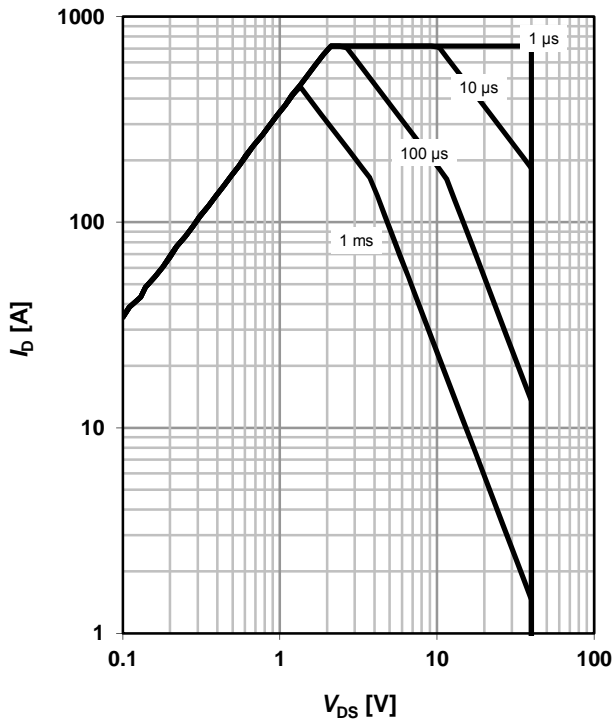
$I_D = f(T_C); V_{GS} \geq 6 V$



3 Safe operating area

$I_D = f(V_{DS}); T_C = 25\text{ °C}; D = 0$

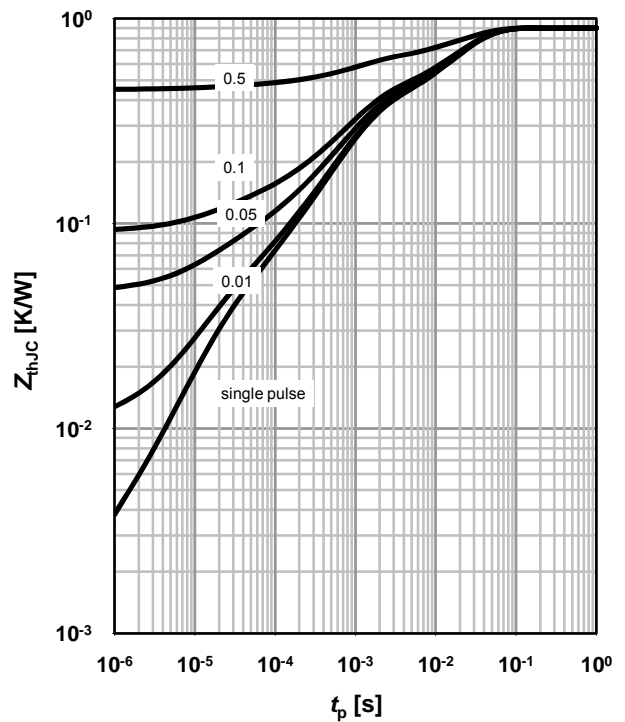
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJC} = f(t_p)$

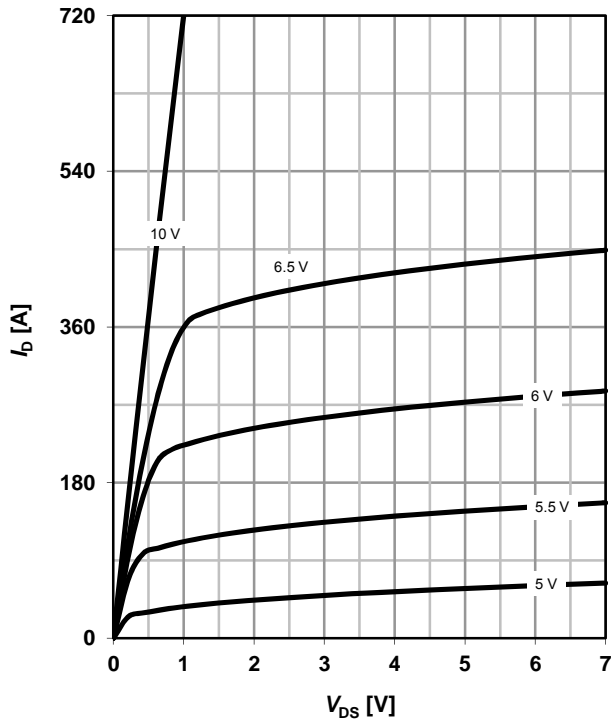
parameter: $D = t_p/T$



5 Typ. output characteristics

$I_D = f(V_{DS}); T_j = 25\text{ }^\circ\text{C}$

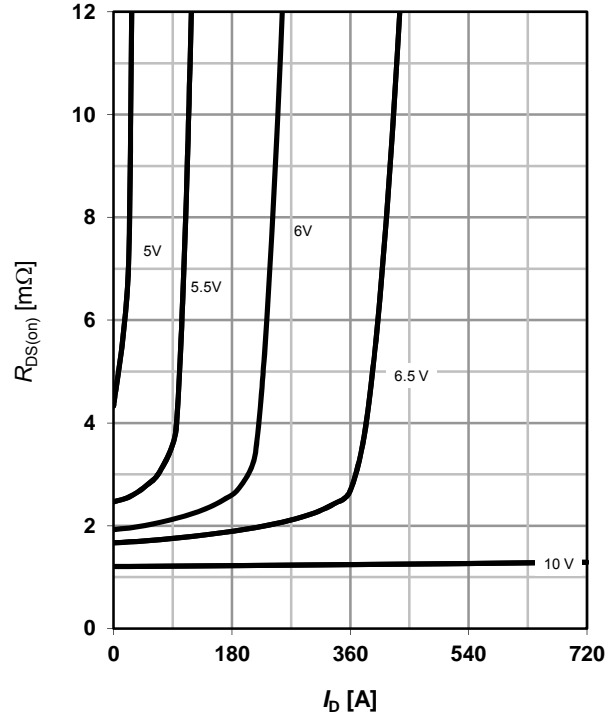
parameter: V_{GS}



6 Typ. drain-source on-state resistance

$R_{DS(on)} = f(I_D); T_j = 25\text{ }^\circ\text{C}$

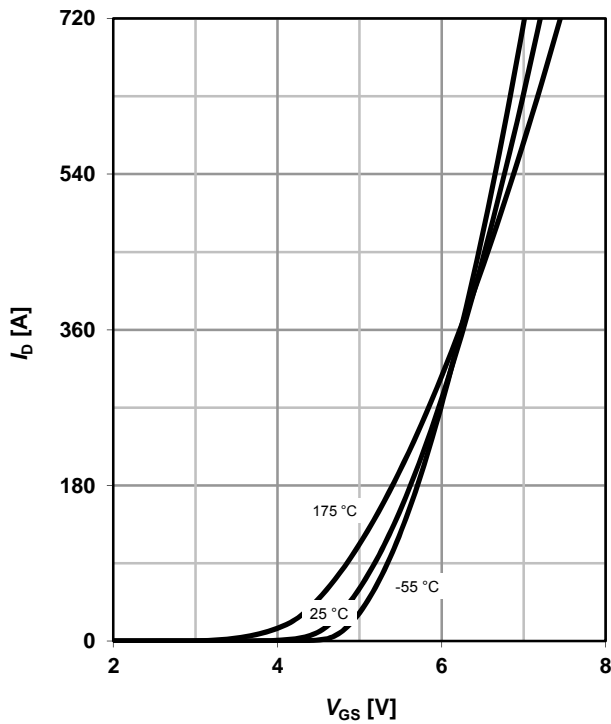
parameter: V_{GS}



7 Typ. transfer characteristics

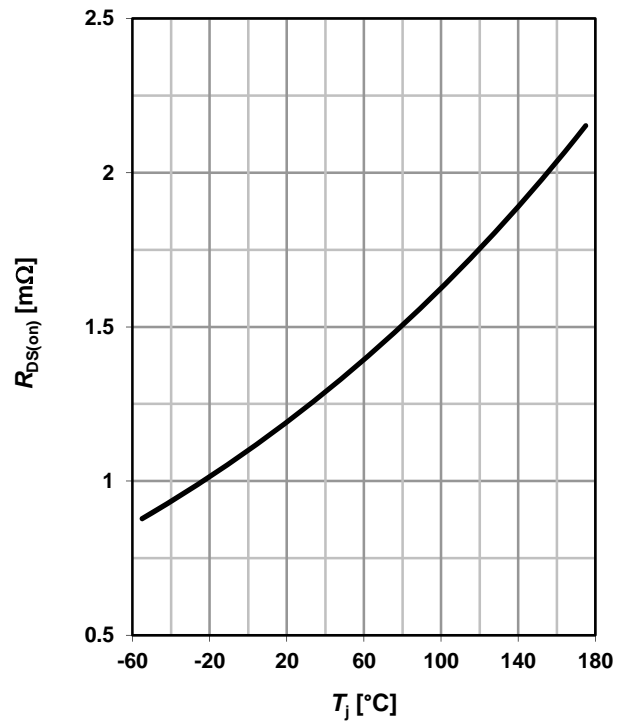
$I_D = f(V_{GS}); V_{DS} = 6\text{ V}$

parameter: T_j



8 Typ. drain-source on-state resistance

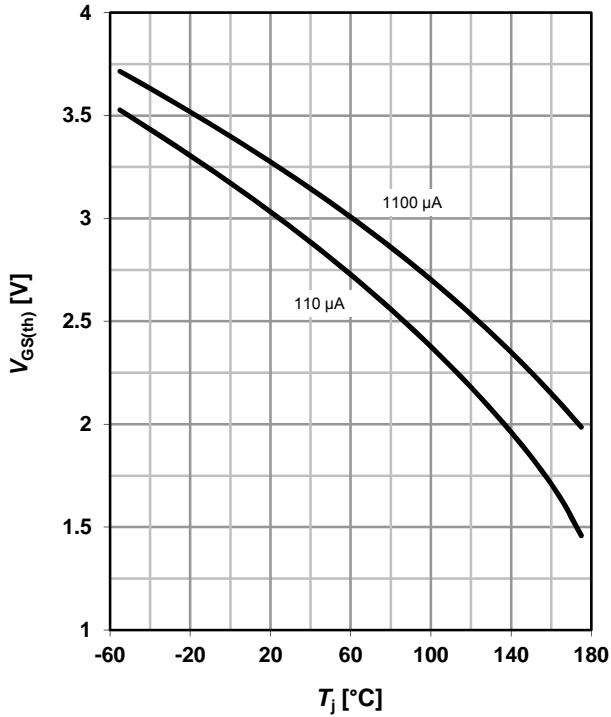
$R_{DS(on)} = f(T_j); I_D = 100\text{ A}; V_{GS} = 10\text{ V}$



9 Typ. gate threshold voltage

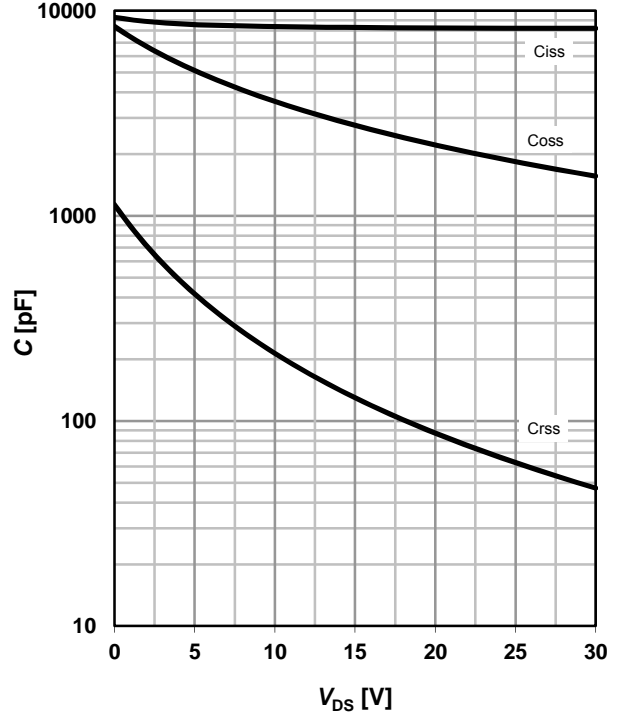
$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$

parameter: I_D



10 Typ. capacitances

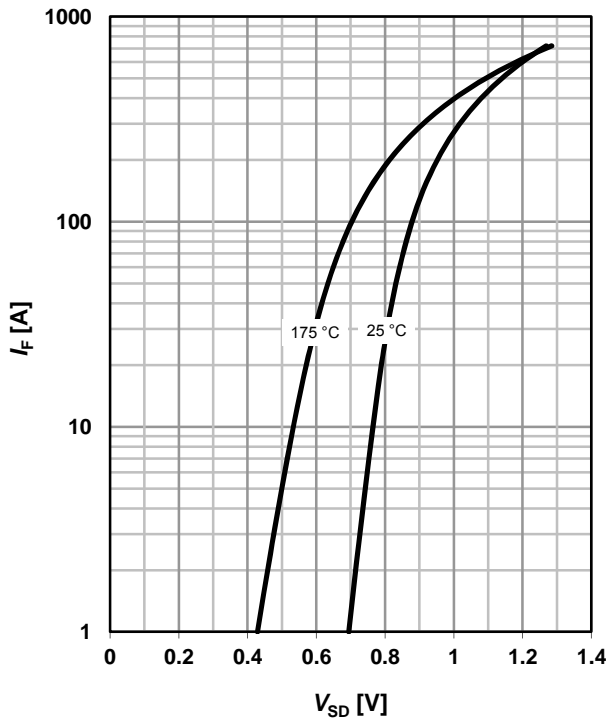
$C = f(V_{DS}); V_{GS} = 0 V; f = 1 MHz$



11 Typical forward diode characteristics

$I_F = f(V_{SD})$

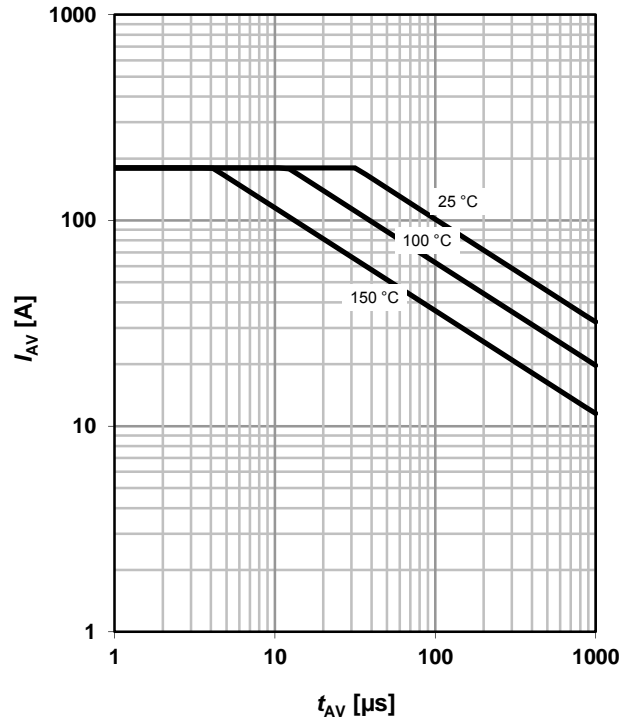
parameter: T_j



12 Typ. avalanche characteristics

$I_{AS} = f(t_{AV})$

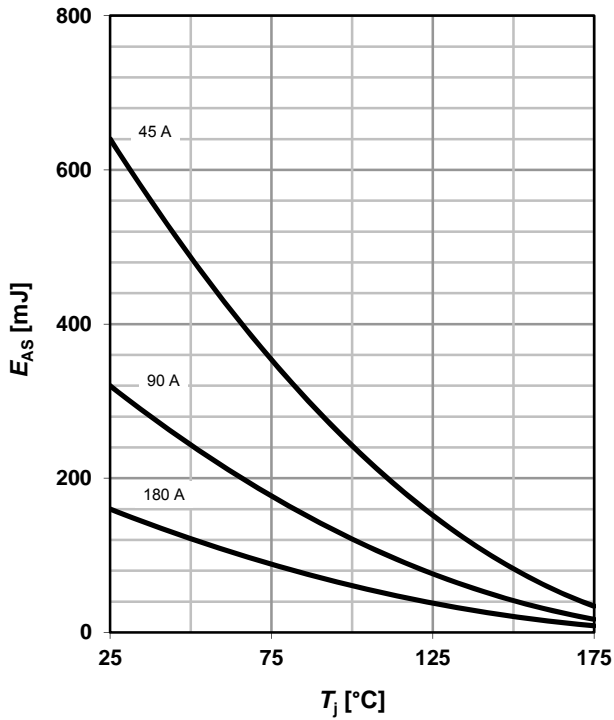
parameter: $T_{j(start)}$



13 Typical avalanche energy

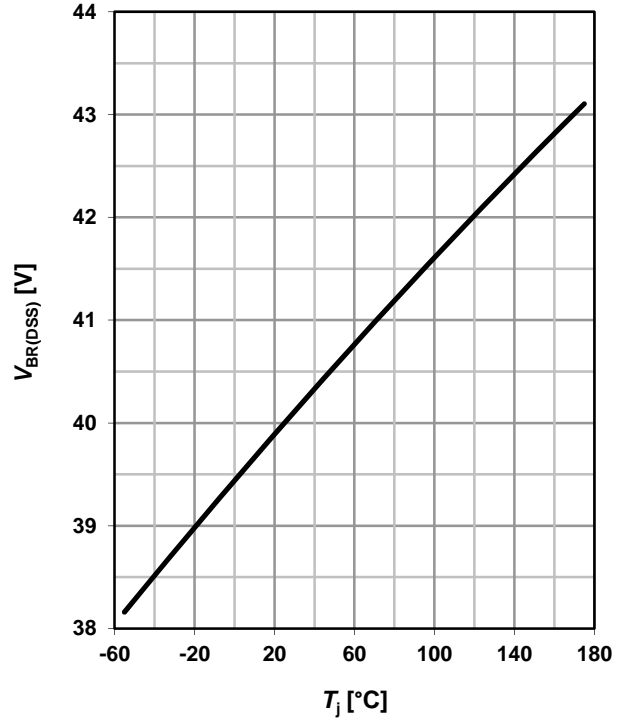
$E_{AS} = f(T_j)$

parameter: I_D



14 Drain-source breakdown voltage

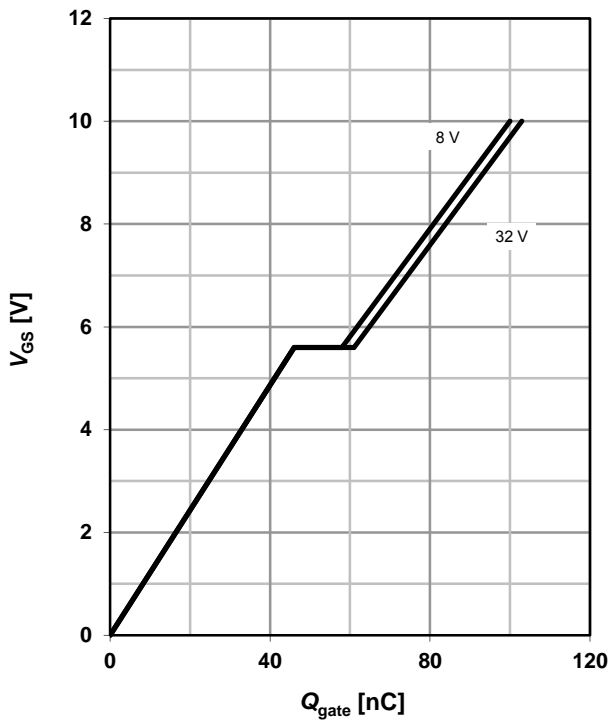
$V_{BR(DSS)} = f(T_j); I_{D_typ} = 1 \text{ mA}$



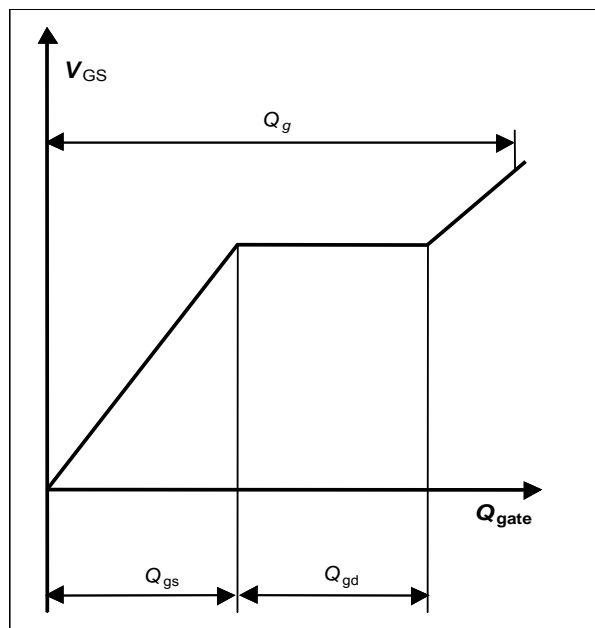
15 Typ. gate charge

$V_{GS} = f(Q_{gate}); I_D = 180 \text{ A pulsed}$

parameter: V_{DD}



16 Gate charge waveforms



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Revision History

Version	Date	Changes
Version 1.0	2018-04-10	Final Datasheet